InfinityLine P+

Modular Vertical Touch-Free Plating.

The InfinityLine P+ is a touch-free, double-sided vertical plating system combining pre-treatment, plating, resist stripping, and rinsing in one modular platform. Segmented anodes, movable panel frames, and optimized vertical flow ensure excellent plating uniformity, while sealed, water-cooled titanium contacts enable reliable connection to ultra-thin seed layers with zero maintenance.

- Uniform plating with optimized electrolyte flow
- SCHMID's innovative clamping frame technology
- Reliable contact for seed layers
- Zero maintenance sealed contacts
- Industry 4.0 ready with MES interface and web-based HMI

Key Performance Indicators

Panel Size	Max 635mm x 635mm / 24.5'' x 24.5'' (Active Area 24'' x 24'')	
Panel Thickness	Minimum	25µm CCL / 200µm glass
	Maximum	2.40mm

Panel Weight	Maximum: 2.4kg
Capabilitiy	Panel Plating / Pattern Plating 0.5 Panel/min at 17µm line height with 2.5 A/dm^2 with 20 plating cells

Other dimensions on demand

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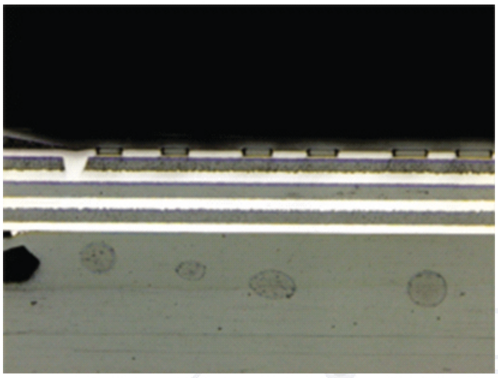
Process Highlights

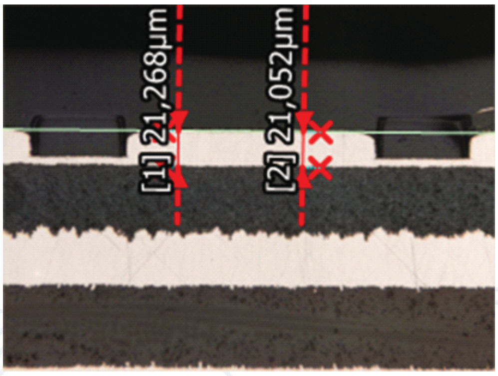
Engineered for precision, flexibility, and performance in next-generation substrate plating.

InfinityLine P+ combines innovative flow control, smart automation, and touch-free handling to ensure maximum quality and uptime.

- Exceptional plating uniformity through segmented anodes and controlled electrolyte flow
- Safe processing of ultra-thin and fragile panels via SCHMID's touch-free clamping system
- Scalable modular design – easily expandable from R&D to HVM
- High throughput with optimized process stability and minimal maintenance
- Full fab integration with FOUP logistics, MES connectivity, and web-based control

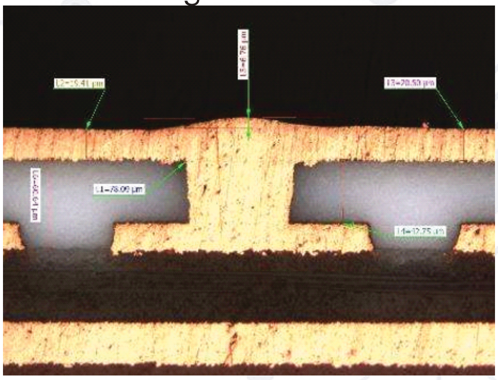
Process Results - mSAP Plating



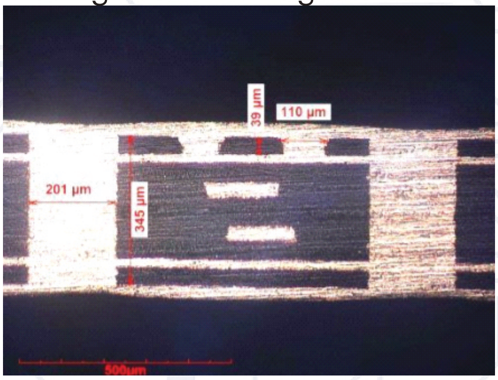


Process Results - Filling

BV Via Filling



Through Hole Filling



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